

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1710	(257/774).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2004/07/07 09:18
S2	10	((("6054380") or ("6046104") or ("6069068") or ("6130161") or ("6184138") or ("6200899") or ("6189209") or ("5994211") or ("6150723") or ("6157081"))).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2004/07/07 10:21
S3	37	((("6204550") or ("6077779") or ("6096637") or ("6130156") or ("6140225") or ("6218279") or ("6225217") or ("6218279") or ("6225217") or ("6242789") or ("6271119") or ("6443743") or ("6569751") or ("5420070") or ("5318924") or ("6146991") or ("5306952") or ("5652182") or ("5514622") or ("5874355") or ("6143649") or ("6225698") or ("6225698") or ("5591672") or ("5915202") or ("6025269") or ("6093645") or ("6177338") or ("4330850") or ("5001079") or ("5429989") or ("5849367") or ("5851581") or ("5975912") or ("6028360") or ("6066557") or ("6093639") or ("6147000") or ("6146996") or ("6211084"))).PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2004/07/07 10:21
S4	10	("20020024142" "20020036309" "5354712" "5472912" "5693564" "6028362" "6211085" "6258707" "6326301" "6436814").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2004/07/07 11:07
S5	66	hamamoto.in. and dram	US-PGPUB; USPAT; USOCR	OR	OFF	2004/07/07 11:07

Most Frequently Occurring Classifications of Patents Returned
From A Search of 10/606,048 on July 07, 2004

Combined Classifications

23 257/E21.584	3 427/99
11 438/637	3 438/618
10 257/E21.577	3 438/623
10 257/E23.145	3 438/628
9 438/643	3 438/634
8 257/E21.585	3 438/639
8 438/627	3 438/642
8 438/672	3 438/654
7 438/624	3 438/658
7 438/648	3 438/700
6 257/774	3 438/735
6 438/622	3 438/736
6 438/629	2 257/622
6 438/687	2 257/764
5 257/E21.311	2 257/775
4 257/E21.578	2 257/E21.313
4 257/E23.16	2 257/E21.576
4 438/597	2 257/E21.583
4 438/626	2 257/E21.589
4 438/631	2 257/E21.591
4 438/633	2 438/131
4 438/645	2 438/132
4 438/649	2 438/257
4 438/653	2 438/28
4 438/660	2 438/467
4 438/666	2 438/529
4 438/680	2 438/601
4 438/685	2 438/625
3 257/751	2 438/630
3 257/758	2 438/638
3 257/763	2 438/644
3 257/E21.033	2 438/655
3 257/E21.256	2 438/656
3 257/E21.257	2 438/663
3 257/E21.294	2 438/675
3 257/E21.314	2 438/678
3 257/E21.579	2 438/681
3 257/E21.582	2 438/682
3 257/E23.149	2 438/688
3 427/124	2 438/720

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- 11 438/637 (5 OR, 6 XR)
Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
- 438/584 COATING WITH ELECTRICALLY OR THERMALLY CONDUCTIVE MATERIAL
 - 438/597 .To form ohmic contact to semiconductive material
 - 438/618 ..Contacting multiple semiconductive regions (i.e., interconnects)
 - 438/622 ...Multiple metal levels, separated by insulating layer (i.e., multiple level metallization)
 - 438/637With formation of opening (i.e., viahole) in insulative layer
- 9 438/643 (1 OR, 8 XR)
Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
- 438/584 COATING WITH ELECTRICALLY OR THERMALLY CONDUCTIVE MATERIAL
 - 438/597 .To form ohmic contact to semiconductive material
 - 438/618 ..Contacting multiple semiconductive regions (i.e., interconnects)
 - 438/642 ...Diverse conductors
 - 438/643At least one layer forms a diffusion barrier
- 8 438/627 (1 OR, 7 XR)
Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
- 438/584 COATING WITH ELECTRICALLY OR THERMALLY CONDUCTIVE MATERIAL
 - 438/597 .To form ohmic contact to semiconductive material
 - 438/618 ..Contacting multiple semiconductive regions (i.e., interconnects)
 - 438/622 ...Multiple metal levels, separated by insulating layer (i.e., multiple level metallization)
 - 438/625At least one metallization level formed of diverse conductive layers
 - 438/627At least one layer forms a diffusion barrier
- 8 438/672 (0 OR, 8 XR)
Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
- 438/584 COATING WITH ELECTRICALLY OR THERMALLY CONDUCTIVE MATERIAL
 - 438/597 .To form ohmic contact to semiconductive material
 - 438/669 ..And patterning of conductive layer
 - 438/672 ...Plug formation (i.e., in viahole)
- 7 438/624 (2 OR, 5 XR)
Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS

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- 438/584 COATING WITH ELECTRICALLY OR THERMALLY
CONDUCTIVE MATERIAL
- 438/597 .To form ohmic contact to semiconductive
material
- 438/618 ..Contacting multiple semiconductive regions
(i.e., interconnects)
- 438/622 ...Multiple metal levels, separated by
insulating layer (i.e., multiple level metallization)
- 438/624Separating insulating layer is laminate or
composite of plural insulating materials
- 7 438/648 (1 OR, 6 XR)
Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
- 438/584 COATING WITH ELECTRICALLY OR THERMALLY
CONDUCTIVE MATERIAL
- 438/597 .To form ohmic contact to semiconductive
material
- 438/618 ..Contacting multiple semiconductive regions
(i.e., interconnects)
- 438/642 ...Diverse conductors
- 438/648Having refractory group metal (i.e.,
titanium (Ti), zirconium (Zr), hafnium (Hf), vanadium (V),
niobium (Nb), tantalum (Ta), chromium (Cr), molybdenum
(Mo), tungsten (W), or alloy thereof)
- 6 257/774 (2 OR, 4 XR)
Class 257 : ACTIVE SOLID-STATE DEVICES
- 257/734 COMBINED WITH ELECTRICAL CONTACT OR LEAD
- 257/773 .Of specified configuration
- 257/774 ..Via (interconnection hole) shape
- 6 438/622 (1 OR, 5 XR)
Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
- 438/584 COATING WITH ELECTRICALLY OR THERMALLY
CONDUCTIVE MATERIAL
- 438/597 .To form ohmic contact to semiconductive
material
- 438/618 ..Contacting multiple semiconductive regions
(i.e., interconnects)
- 438/622 ...Multiple metal levels, separated by
insulating layer (i.e., multiple level metallization)
- 6 438/629 (2 OR, 4 XR)
Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS
- 438/584 COATING WITH ELECTRICALLY OR THERMALLY
CONDUCTIVE MATERIAL
- 438/597 .To form ohmic contact to semiconductive
material
- 438/618 ..Contacting multiple semiconductive regions
(i.e., interconnects)
- 438/622 ...Multiple metal levels, separated by
insulating layer (i.e., multiple level metallization)
- 438/625At least one metallization level formed of

diverse conductive layers
438/629Diverse conductive layers limited to
viahole/plug

6 438/687 (4 OR, 2 XR)

Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING: PROCESS

438/584 COATING WITH ELECTRICALLY OR THERMALLY
CONDUCTIVE MATERIAL

438/597 .To form ohmic contact to semiconductive
material

438/687 ..Copper of copper alloy conductor

PLUS Search Results for S/N 10/606,048, Searched July 07, 2004 (Top 50)

The Patent Linguistics Utility System (PLUS) is a USPTO automated search system for U.S. Patents from 1971 to the present. PLUS is a query-by-example search system which produces a list of patents that are most closely related linguistically to the application searched. This search was prepared by the staff of the Scientific and Technical Information Center, SIRA.

6054380	6204550	6271119	6143649	5429989
6046104	6077779	6443743	6225698	5849367
6069068	6096637	6569751	6225698	5851581
6130161	6130156	5420070	5591672	5975912
6184138	6140225	5318924	5915202	6028360
6200899	6218279	6146991	6025269	6066557
6189209	6225217	5306952	6093645	6093639
5994211	6218279	5652182	6177338	6147000
6150723	6225217	5514622	4330850	6146996
6157081	6242789	5874355	5001079	6211084